# 3.3V Differential LVPECL to LVTTL Translator

The MC100EPT21 is a Differential LVPECL to LVTTL translator. Because LVPECL (Positive ECL) levels are used only +3.3 V and ground are required. The small outline 8–lead SOIC package makes the EPT21 ideal for applications which require the translation of a clock or data signal.

The  $V_{BB}$  output allows the EPT21 to be cap coupled in either single–ended or differential input mode. When single–ended cap coupled,  $V_{BB}$  output tied to the D0 input for a non–inverting buffer or the D0 input for an inverting buffer. When cap coupled differentially,  $V_{BB}$  output is connected through a resistor to each input pin. If used, the  $V_{BB}$  pin should be bypassed to  $V_{CC}$  via a 0.01  $\mu F$  capacitor. For additional information see AND8020. For a single–ended direct connection use an external voltage reference source such as a resistor divider. Do not use  $V_{BB}$  for a single–ended direct connection.

- 1.4 ns Typical Propagation Delay
- Maximum Frequency > 275 MHz Typical
- 24 mA TTL outputs
- Operating Range:  $V_{CC} = 3.0 \text{ V}$  to 3.6 V with GND = 0 V
- Open Input Default State
- Q Output Will Default LOW with Inputs Open or at GND
- The 100 Series Contains Temperature Compensation
- V<sub>BB</sub> Output
- New Differential Input Common Mode Range



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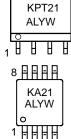
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8 A A A A



SO-8 D SUFFIX CASE 751



8 **(1)** 

TSSOP-8 DT SUFFIX CASE 948R

A = Assembly Location

L = Wafer Lot

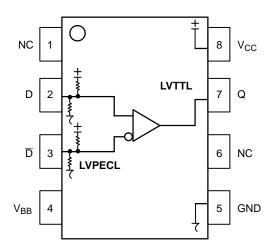
Y = Year

W = Work Week

### **ORDERING INFORMATION**

Device	Package	Shipping
MC100EPT21D	SO-8	98 Units/Rail
MC100EPT21DR2	SO-8	2500 Tape & Reel
MC100EPT21DT	TSSOP-8	100 Units/Rail
MC100EPT21DTR2	TSSOP-8	2500 Tape & Reel

<sup>\*</sup>For additional information, see Application Note AND8002/D



# PIN DESCRIPTION

PIN	FUNCTION
Q	LVTTL Output
D**, \( \overline{D}**	Differential LVPECL Input Pair
V <sub>CC</sub>	Positive Supply
V <sub>BB</sub>	Output Reference Voltage
GND	Ground
NC	No Connect

<sup>\*\*</sup> Pins will default to V<sub>CC</sub>/2 when left open.

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

#### **ATTRIBUTES**

Characteris	Characteristics			
Internal Input Pulldown Resistor	75 kΩ			
Internal Input Pullup Resistor	37.5 kΩ			
ESD Protection	> 1.5 kV > 100 V > 2 kV			
Moisture Sensitivity, Indefinite Time (	Out of Drypack (Note 1)	Level 1		
Flammability Rating Oxygen Index	UL-94 code V-0 A 1/8" 28 to 34			
Transistor Count	81 Devices			
Meets or exceeds JEDEC Spec EIA	JESD78 IC Latchup Test			

<sup>1.</sup> For additional information, see Application Note AND8003/D.

# MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>CC</sub>	PECL Power Supply	GND = 0 V		3.8	V
V <sub>IN</sub>	PECL Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	0 to 3.8	V
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
TA	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W
$\theta_{\text{JC}}$	Thermal Resistance (Junction to Case)	std bd	8 SOIC	41 to 44	°C/W
$\theta_{JA}$	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W
$\theta_{JC}$	Thermal Resistance (Junction to Case)	std bd	8 TSSOP	41 to 44	°C/W
T <sub>sol</sub>	Wave Solder	<2 to 3 sec @ 248°C		265	°C

<sup>2.</sup> Maximum Ratings are those values beyond which device damage may occur.

#### MC100FPT21

# PECL INPUT DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$ , GND = 0.0 V (Note 3)

				-40°C			25°C			85°C		
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (Single Ended)		2075		2420	2075		2420	2075		2420	mV
V <sub>IL</sub>	Input LOW Voltage (Single Ended)		1355		1675	1355		1675	1355		1675	mV
$V_{BB}$	Output Voltage Reference		1775	1875	1975	1775	1875	1975	1775	1875	1975	V
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential) (Note 4)		2.0		3.3	2.0		3.3	2.0		3.3	V
I <sub>IH</sub>	Input HIGH Current				150			150			150	μΑ
I <sub>IL</sub>		D D	-150		0.5	-150		0.5	-150		0.5	μА

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

# TTL OUTPUT DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$ , GND = 0.0 V, $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OH</sub>	Output HIGH Voltage (Note 5)	$I_{OH} = -3.0 \text{ mA}$	2.4			V
V <sub>OL</sub>	Output LOW Voltage (Note 5)	I <sub>OL</sub> = 24 mA			0.5	V
I <sub>CCH</sub>	Power Supply Current	Outputs set to HIGH	5	12	20	mA
I <sub>CCL</sub>	Power Supply Current	Outputs set to LOW	8	18	26	mA
Ios	Output Short Circuit Current		-130		-80	mA

<sup>5.</sup> All loading with 500 ohms to GND.

#### AC CHARACTERISTICS $V_{CC} = 3.0 \text{ V}$ to 3.6 V, GND = 0.0 V (Note 6)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Frequency (See Figure 2. F <sub>max</sub> /JITTER)	275	350		275	350		275	350		MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	$  \begin{array}{ll} \mbox{Propagation Delay to} \\ \mbox{Output Differential} & \mbox{$C_L$ = 20 pf} \end{array} $	1200 1200	1450 1400	1800 1800	1200 1200	1450 1400	1800 1800	1300 1200	1450 1400	1900 1900	ps
t <sub>SK++</sub> t <sub>SK</sub> t <sub>SKPP</sub>	Output-to-Output Skew++ Output-to-Output Skew Part-to-Part Skew (Note 7)			60 25 500			60 25 500			60 25 500	ps
t <sub>JITTER</sub>	Cycle-to-Cycle Jitter (See Figure 2. F <sub>max</sub> /JITTER)		0.2	< 1		0.2	< 1		0.2	< 1	ps
$V_{PP}$	Input Voltage Swing (Differential)	150	800	1200	150	800	1200	150	800	1200	mV
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Times $C_L = 20 \text{ pf}$ (0.8V - 2.0V) $Q, \overline{Q}$	330	500	900	330	500	900	330	500	900	ps

<sup>6.</sup> Measured using a 750 mV source, 50% duty cycle clock source. All loading with 500 ohms to GND,  $C_L = 20 \text{ pF}$ .

Input parameters vary 1:1 with V<sub>CC</sub>.
 V<sub>IHCMR</sub> min varies 1:1 with GND, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

<sup>7.</sup> Skews are measured between outputs under identical transitions.

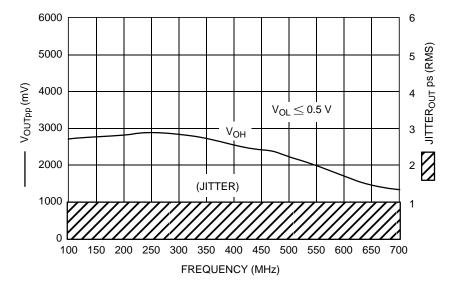


Figure 2. F<sub>max</sub>/Jitter

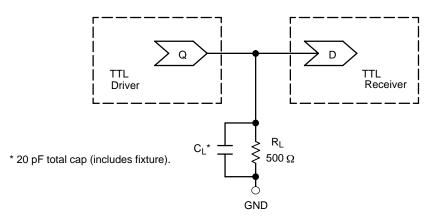


Figure 3. TTL Output Loading Used For Device Evaluation

# **Resource Reference of Application Notes**

AN1404 – ECLinPS Circuit Performance at Non–Standard V<sub>IH</sub> Levels

AN1405 – ECL Clock Distribution Techniques

AN1406 – Designing with PECL (ECL at +5.0 V)

AN1503 - ECLinPS I/O SPICE Modeling Kit

AN1504 – Metastability and the ECLinPS Family

AN1560 – Low Voltage ECLinPS SPICE Modeling Kit

AN1568 - Interfacing Between LVDS and ECL

AN1596 - ECLinPS Lite Translator ELT Family SPICE I/O Model Kit

AN1650 - Using Wire-OR Ties in ECLinPS Designs

AN1672 - The ECL Translator Guide

AND8001 - Odd Number Counters Design

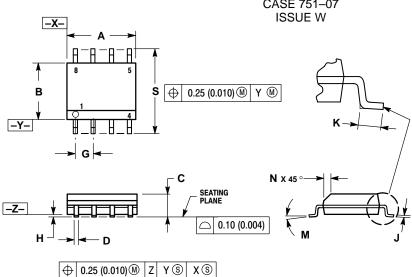
AND8002 - Marking and Date Codes

AND8020 - Termination of ECL Logic Devices

For an updated list of Application Notes, please see our website at http://onsemi.com.

# **PACKAGE DIMENSIONS**

# SO-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-07

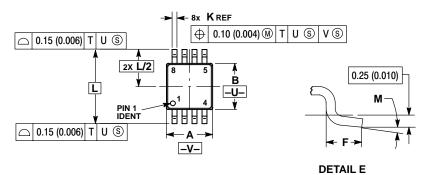


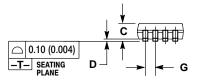
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

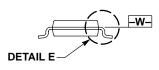
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35 1.75		0.053	0.069	
D	0.33	0.33 0.51		0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 ° 8 °		0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

#### **PACKAGE DIMENSIONS**

#### TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**







#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. TERMINAL NI IMBERS ARE SHOWN FOR

- FER SIDE.

  5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

  6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65	BSC	0.026	BSC
K	0.25	0.40	0.010	0.016
L	4.90	BSC	0.193	BSC
M	0°	6 °	0°	6°



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